

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5744712

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SUNG-HYUP LEE	09/20/2019
JAE-WOON LEE	06/16/2019
YONG-SEOK LEE	09/20/2019
YANG-JEAN PARK	06/19/2019
JIN-WOO PARK	06/19/2019
RECEIVING PARTY DATA	
Name:	SAMSUNG ELECTRONICS CO., LTD.
Street Address:	129, SAMSUNG-RO, YEONGTONG-GU, SUWON-SI,
City:	GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
Name:	HYUPJINCONNECTOR CO., LTD.
Street Address:	16, EMTIBEUI 12-RO, DANWON-GU, ANSAN-SI,
City:	GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16499378
CORRESPONDENCE DATA	
Fax Number:	(201)226-9246
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	201-226-9245
Email:	gabriella.zisa@chareiter.com
Correspondent Name:	CHA & REITER, LLC
Address Line 1:	17 ARCADIAN AVENUE
Address Line 2:	SUITE 208
Address Line 4:	PARAMUS, NEW JERSEY 07652
ATTORNEY DOCKET NUMBER:	5000-1-1907
NAME OF SUBMITTER:	STEVE CHA

SIGNATURE:	/Steve Cha/
DATE SIGNED:	09/30/2019
Total Attachments: 4 source=5000-1-1907_Assignment#page1.tif source=5000-1-1907_Assignment#page2.tif source=5000-1-1907_Assignment#page3.tif source=5000-1-1907_Assignment#page4.tif	

Docket No.: P23761-US (GM-201612-012-1-US0)

PTO/SB/15

Assignment of Invention and Patent Application

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration,

- 1) **Sung-Hyup LEE** of
#215-902, Botdeulmaeul 2-danji EG The One APT., 393, Pangyo-ro, Bundang-gu, Seongnam-si, Gyeonggi-do, 13490, Republic of Korea
- 2) **Jae-Woon LEE** of
#811-601, Daewoo Prugio 8-cha APT., 9, Woncho-ro, Danwon-gu, Ansan-si, Gyeonggi-do, 15373, Republic of Korea
- 3) **Yong-Seok LEE** of
#102-701, Ssangyong Sweet Dot Home 1-cha APT., 10, Ogeum-ro 62-gil, Songpa-gu, Seoul, 05773, Republic of Korea
- 4) **Yang-Jean PARK** of
#515-1903, Suwon Homaesil Humansia 5-danji APT., 46, Geumgok-ro, Gwonseon-gu, Suwon-si, Gyeonggi-do, 16385, Republic of Korea
- 5) **Jin-Woo PARK** of
#201-202, Pangyo Unjung Apfelbaum 2-cha APT., 23, Haogae-ro 351beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, 13455, Republic of Korea

(hereinafter **Assignor**) hereby sells, assigns, transfers, and sets over unto:

1st Applicant: SAMSUNG ELECTRONICS CO., LTD. of
129, SAMSUNG-RO, YEONGTONG-GU, SUWON-SI, GYEONGGI-DO, 16677,
REPUBLIC OF KOREA

2nd Applicant: HYUPJINCONNECTOR CO., LTD of
16, EMTIBEUI 12-RO, DANWON-GU, ANSAN-SI, GYEONGGI-DO, 15655,
REPUBLIC OF KOREA

(hereinafter **Assignee**) the entire right, title and interest for the United States Of America as defined in 35 U.S.C. Section 261, in and to the invention entitled as:

“MULTI-CONNECTION DEVICE”

invented by **Assignor**; the application for United States patent therefor, invented by **Assignor**;

Docket No.: P23761-US (GM-201612-012-1-US0)

any patent or reissues of any patent that may be granted thereon; and any applications which are continuations, continuation-in-part, substitutes, or divisions of said application. **Assignor** authorizes **Assignee** to enter the date of signature and/or Serial Number and Filing Date in the above. **Assignor** also authorizes and requests the Commissioner of Patents and Trademarks to issue any resulting patent(s) to the said **Assignee**, for its interests as **Assignee**, its successors, assigns and legal representatives. The undersigned agrees that the attorney of record in said application shall hereafter act on behalf of said **Assignee**; and **Assignor** further conveys to **Assignee** all priority rights resulting from the above-identified application for United States Patent. **Assignor** agrees to execute all papers, give any required testimony and perform other lawful acts, as deemed essential by **Assignee** to perfect **Assignee's** interest in any resulting patent of the United States, and to acquire, hold, enforce, convey, and uphold the validity of said patent and reissues and extensions thereof, and **Assignee's** interest therein.

SIGNED ON THE DATES(S) INDICATED BESIDE MY/OUR SIGNATURE(S):


Name of first Inventor: Sung-Hyup LEE

Signature of inventor

Dated: _____

WITNESSED: _____

Name of second Inventor: Jae-Woon LEE



Signature of inventor

Dated: 19. 6. 19

WITNESSED: _____

Name of third Inventor: Yong-Seok LEE

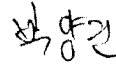
Signature of inventor

Dated: _____

WITNESSED: _____

Docket No.: P23761-US (GM-201612-012-1-US0)

Name of fourth Inventor: Yang-Jean PARK

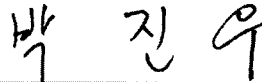


Signature of inventor

Dated: 19. 6. 19

WITNESSED: _____

Name of fifth Inventor: Jin-Woo PARK



Signature of inventor

Dated: 19. 6. 19

WITNESSED: _____

Full name of first inventor: **Sung-Hyup LEE**
Residence Address: #215-902, Botdeulmaeul 2-danji EG The One APT., 393, Pangyo-ro, Bundang-gu, Seongnam-si, Gyeonggi-do, 13490, Republic of Korea

Post office address: Same as above

Date: 2019.09.20

Signature: Lee Sung Hyup

Full name of second inventor: **Jae-Woon LEE**
Residence Address: #811-601, Daewoo Prugio 8-cha APT., 9, Woncho-ro, Danwon-gu, Ansan-si, Gyeonggi-do, 15373, Republic of Korea

Post office address: Same as above

Date: _____

Signature: _____

Full name of third inventor: **Yong-Seok LEE**
Residence Address: #102-701, Ssangyong Sweet Dot Home 1-cha APT., 10, Ogeum-ro 62-gil, Songpa-gu, Seoul, 05773, Republic of Korea

Post office address: Same as above

Date: 2019.09.20

Signature: Lee yong seok